

M5M5279P, J-20, -25, -35, -25L, -35L

294912-BIT (32768-WORD BY 9-BIT) CMOS STATIC RAM

DESCRIPTION

The M5M5279 is a family of 32768-word by 9-bit static RAMs, fabricated with the high-performance CMOS silicon-gate MOS process and designed for high-speed application. These devices operate on a single 5V supply, and are directly TTL compatible. They include a power-down feature as well.

FEATURES

- Fast access time
 - M5M5279P, J-20 20ns(max)
 - M5M5279P, J-25, 25L 25ns(max)
 - M5M5279P, J-35, 35L 35ns(max)
- Low power dissipation
 - Active 300mW(typ)
 - Stand by(-20, 25, 35) 5mW(typ)
 - Stand by(-25L, 35L) 50μW(typ)
- Power down by $\overline{S_1}$
- Single 5V power supply
- Fully static operation
- Requires neither external clock nor refreshing
- All inputs and outputs are directly TTL compatible
- Easy memory expansion by chip-select ($\overline{S_1}$, S_2) input
- Output enable (\overline{OE}) prevents data contention in the I/O bus
- All address inputs are changeable with each other

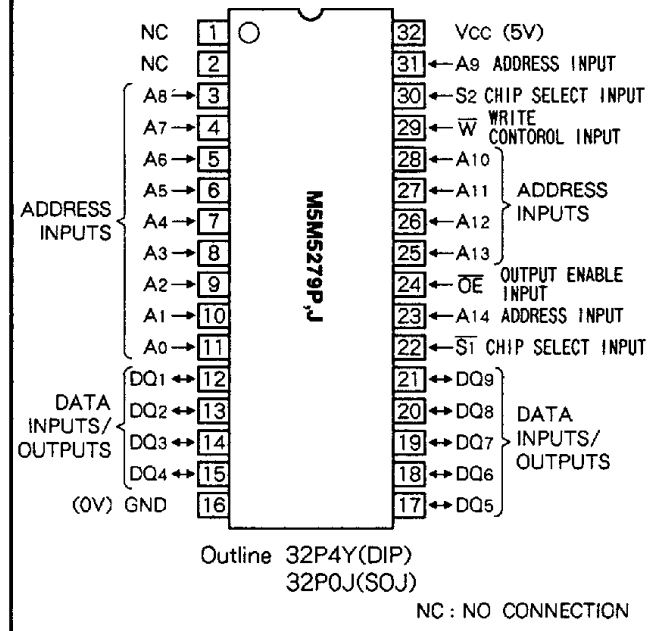
APPLICATION

High-speed memory systems

FUNCTION

A write operation is executed during the $\overline{S_1}$ low, S_2 high, and \overline{W} low overlap time. In this period, address signals must be stable. When \overline{W} is low, the DQ terminal is maintained in the high impedance state.

PIN CONFIGURATION (TOP VIEW)

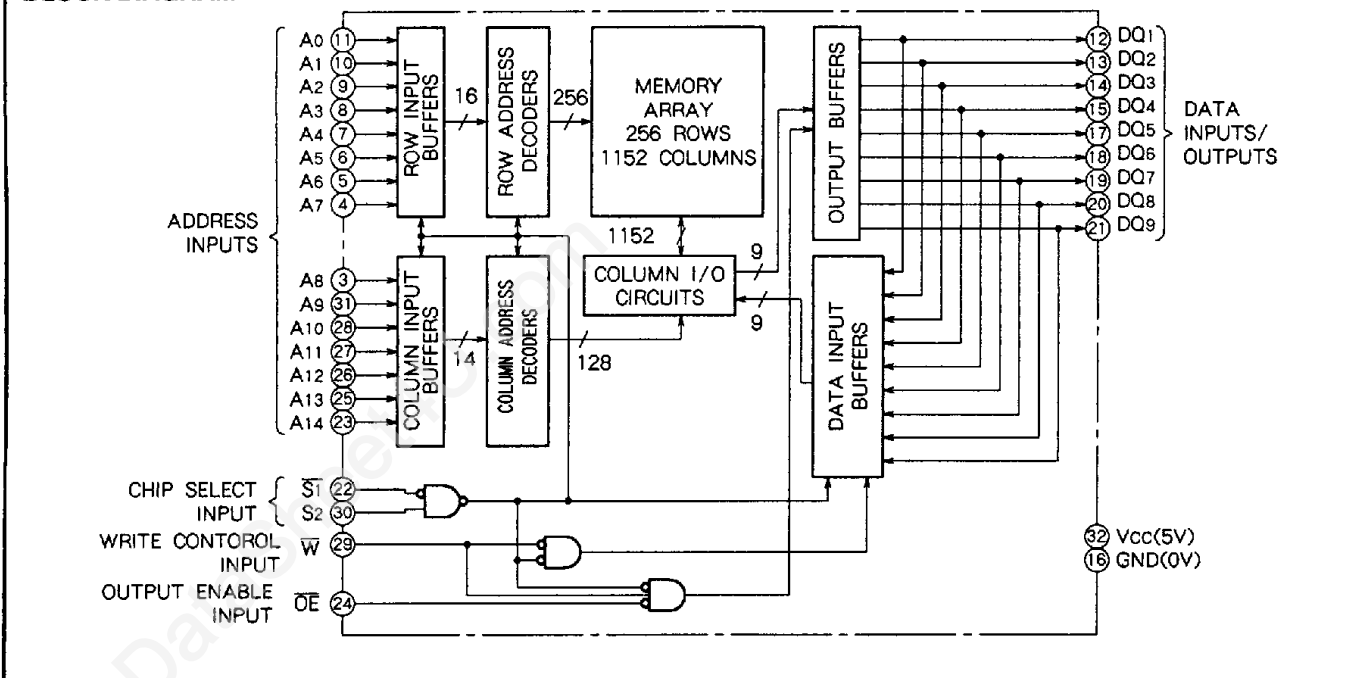


In a read operation, after setting \overline{W} to high, $\overline{S_1}$ to low S_2 high and \overline{OE} to low if the address signals are stable, the data is available at the DQ terminal.

When $\overline{S_1}$ is high, or S_2 is low, the chip is in the non-selectable state, disabling both reading and writing. In this case the output is in the floating (high-impedance) state, useful for OR-ties with other devices.

Signal $\overline{S_1}$ controls the power-down feature. When $\overline{S_1}$ goes high, power dissipation is reduced extremely. The access time from $\overline{S_1}$ is equivalent to the address access time.

BLOCK DIAGRAM



MODE SELECTION

\overline{S}_1	S_2	\overline{W}	\overline{OE}	Mode	Data input/output	I_{CC}
H	X	X	X	Non selection	High-impedance	Stand by
L	L	X	X	Non selection	High-impedance	Active
L	H	L	X	Write	Din	Active
L	H	H	L	Read	Dout	Active
L	H	H	H		High-impedance	Active

H: V_{IH} L: V_{IL} X: V_{IH} or V_{IL}

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V_{CC}	Supply voltage	With respect to GND	-3.5*~7	V
V_I	Input voltage		-3.5*~7	V
V_O	Output voltage		-3.5*~7	V
P_d	Maximum power dissipation		1	W
T_{opr}	Operating temperature		0~70	°C
$T_{stg(bias)}$	Storage temperature (bias)		-10~85	°C
T_{stg}	Storage temperature		-65~150	°C

* Pulse width \leq 20ns, In case of DC: -0.5V

DC ELECTRICAL CHARACTERISTICS ($T_a = 0\sim 70^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V_{IH}	High-level input voltage		2.2		$V_{CC}+0.3$	V
V_{IL}	Low-level input voltage		-0.5*		0.8	V
V_{OH}	High-level output voltage	$I_{OH} = -4\text{mA}$	2.4			V
V_{OL}	Low-level output voltage	$I_{OL} = 8\text{mA}$			0.4	V
I_I	Input current	$V_I = 0\sim V_{CC}$			2	μA
$ I_{OZ} $	Off-state output current	$V_{I(S)} = V_{IH}, V_O = 0\sim V_{CC}$			10	μA
I_{CC1}	Supply current from V_{CC}	$V_{I(S)} = V_{IL}$ Output open	AC(20ns cycle)		140	mA
			AC(25ns cycle)		130	
			AC(35ns cycle)		120	
			DC	75	100	
I_{CC2}	Stand by current	$V_{I(S)} = V_{IH}$	AC(20, 25, 35ns cycle)		40	mA
			Other $V_I \geq V_{IH}$ or $\leq V_{IL}$		30	
I_{CC3}	Stand by current	$V_{I(S)} = V_{CC} - 0.2V$ Other $V_I \leq 0.2V$ or $V_I \geq V_{CC} - 0.2V$	-20, -25, -35	1	10	mA
			-25L, -35L	10	100	

Note 1. Current flow into an IC is positive, out is negative. * -3.0V in case of AC(Pulse width \leq 20ns)

CAPACITANCE

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
C_i	Input capacitance	$V_I = \text{GND}, V_I = 25\text{mVrms}, f = 1\text{MHz}$			5	pF
C_o	Output capacitance	$V_O = \text{GND}, V_O = 25\text{mVrms}, f = 1\text{MHz}$			7	pF

AC ELECTRICAL CHARACTERISTICS ($T_a = 0\sim 70^\circ\text{C}$, $V_{CC} = 5V \pm 10\%$, unless otherwise noted)

(1) MEASUREMENT CONDITIONS

Input pulse levels $V_{IH} = 3V, V_{IL} = 0V$
 Input rise and fall time 3ns
 Input timing reference levels $V_{IH} = 2.4V, V_{IL} = 0.6V$
 Output timing reference levels $V_{OH} = 2.0V, V_{OL} = 0.8V$
 Output loads Fig.1, Fig.2

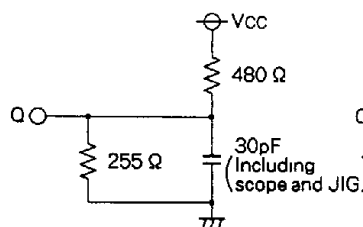


Fig.1 Output load

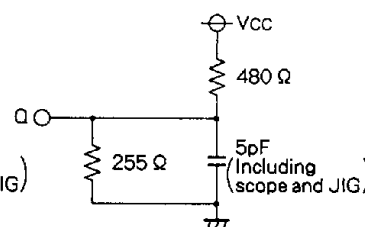


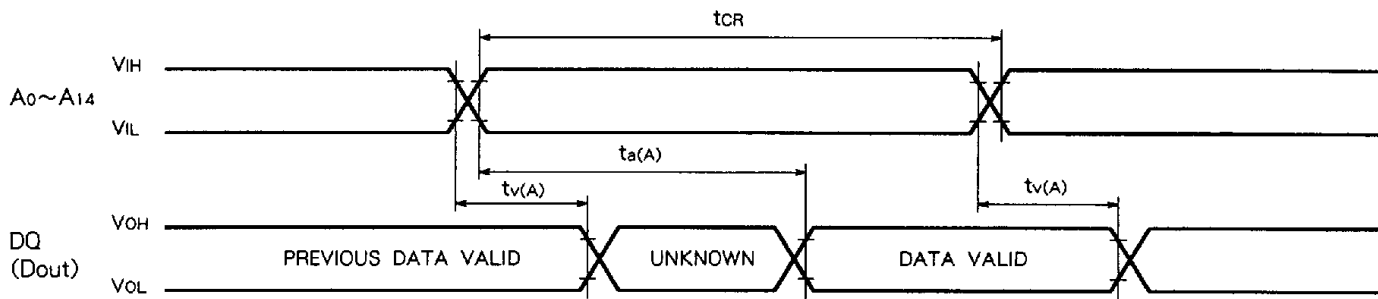
Fig.2 Output load for t_{en}, t_{dis}

(2) READ CYCLE

Symbol	Parameter	Limits						Unit
		M5M5279-20		M5M5279-25, -25L		M5M5279-35, -35L		
		Min	Max	Min	Max	Min	Max	
t _{CR}	Read cycle time	20		25		35		ns
t _{a(A)}	Address access time		20		25		35	ns
t _{a(S1)}	Chip select 1 access time		20		25		35	ns
t _{a(S2)}	Chip select 2 access time		17		22		27	ns
t _{a(OE)}	Output enable access time		10		12		15	ns
t _{v(A)}	Data valid time after address change	3		5		5		ns
t _{en(S1)}	Output enable time after $\overline{S1}$ low	3		5		5		ns
t _{en(S2)}	Output enable time after S ₂ high	0		0		0		ns
t _{en(OE)}	Output enable time after \overline{OE} low	0		0		0		ns
t _{dis(S1)}	Output disable time after $\overline{S1}$ high	0	8	0	10	0	10	ns
t _{dis(S2)}	Output disable time after S ₂ low	0	8	0	10	0	10	ns
t _{dis(OE)}	Output disable time after \overline{OE} high	0	8	0	10	0	10	ns
t _{PU}	Power-up time after chip selection	0		0		0		ns
t _{PD}	Power-down time after chip selection		20		25		35	ns

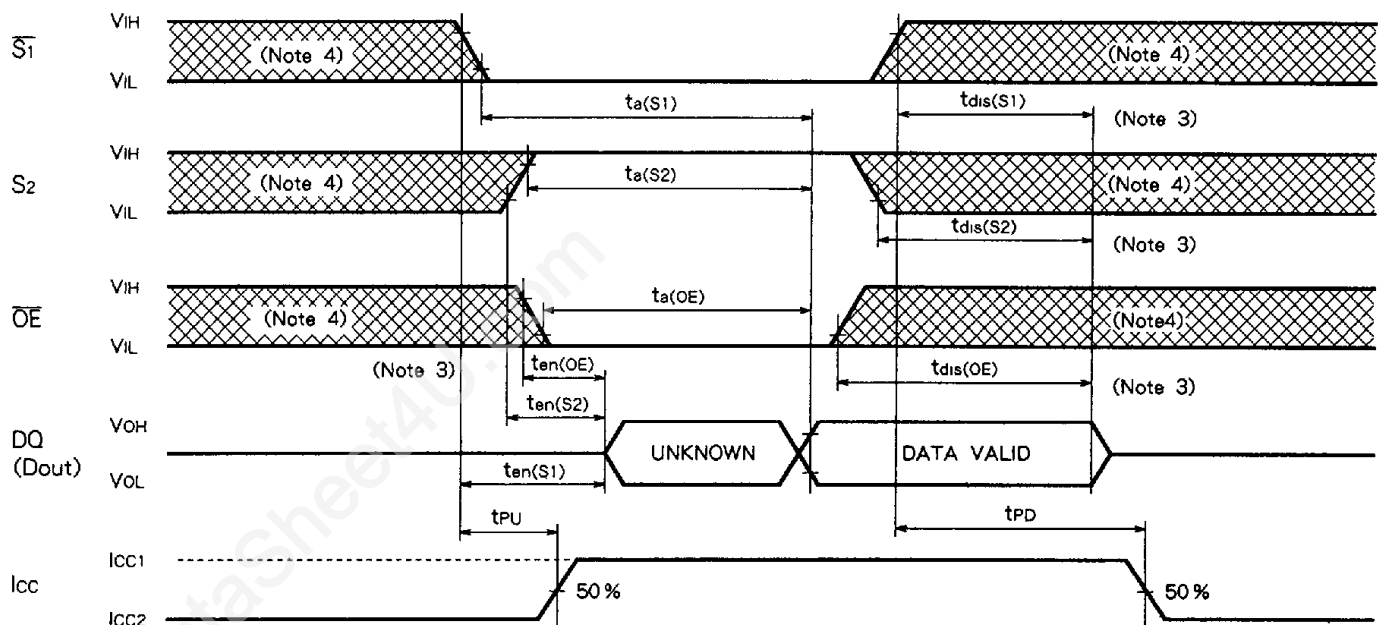
(3) TIMING DIAGRAMS FOR READ CYCLE

Read cycle 1



$\overline{W} = H$ $\overline{S1} = L$ $S2 = H$ $\overline{OE} = L$

Read cycle 2 (Note 2)



Note 2. Addresses valid prior to or coincident with $\overline{S1}$ transition low.

Note 3. Transition is measured ± 500 mV from steady state voltage with specified loading in Figure 2.

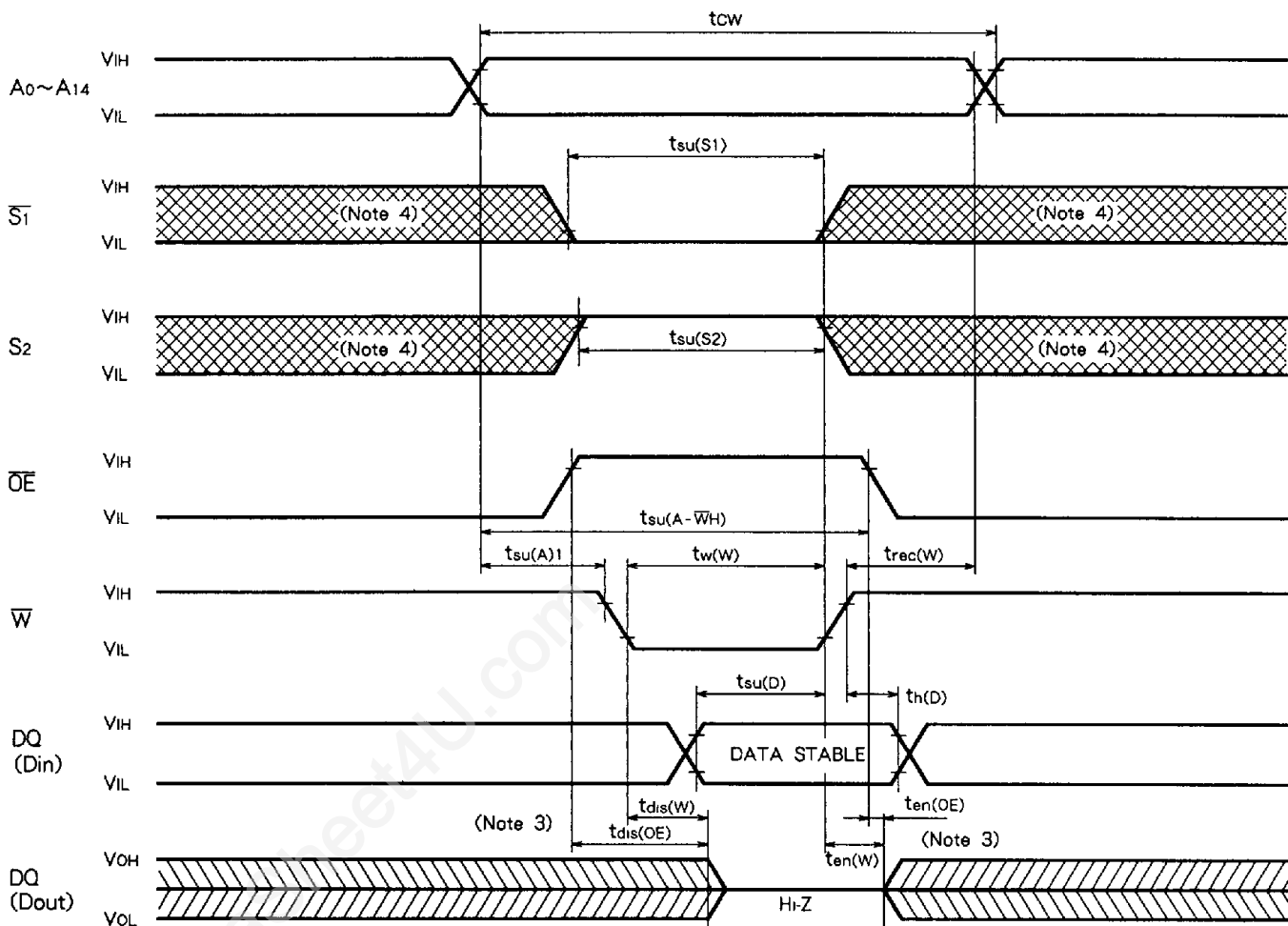
Note 4. Hatching indicates the state is don't care.

(4) WRITE CYCLE

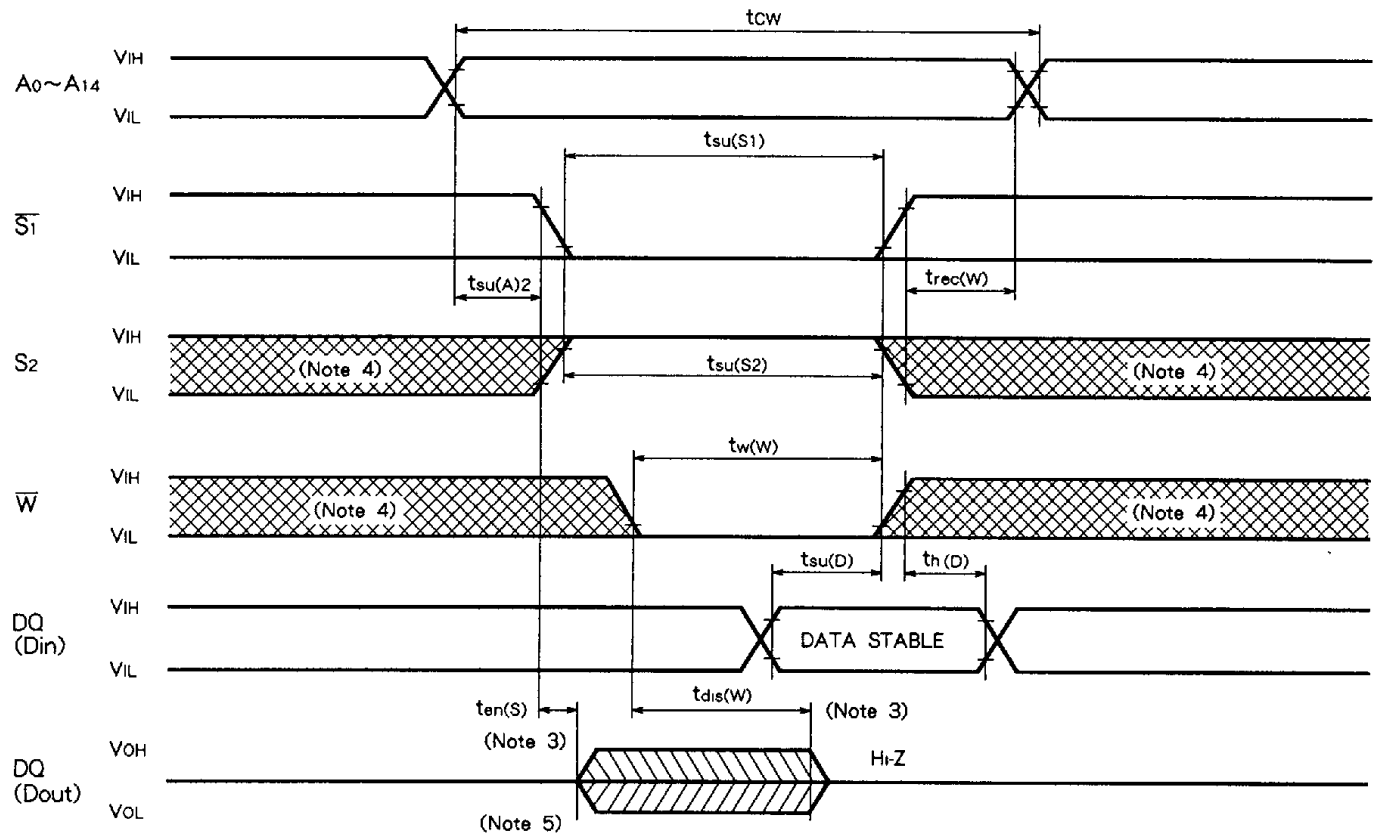
Symbol	Parameter	Limits						Unit
		M5M5279-20		M5M5279-25, -25L		M5M5279-35, -35L		
		Min	Max	Min	Max	Min	Max	
tcw	Write cycle time	20		25		35		ns
tsu(S1)	Chip select 1 setup time	15		20		30		ns
tsu(S2)	Chip select 2 setup time	15		20		30		ns
tsu(A)1	Address setup time(\overline{W})	0		0		0		ns
tsu(A)2	Address setup time($\overline{S1}$, $S2$)	0		0		0		ns
tw(W)	Write pulse width	15		20		25		ns
trec(W)	Write recovery time	0		0		0		ns
tsu(D)	Data setup time	8		10		15		ns
th(D)	Data hold time	0		0		0		ns
tdis(W)	Output disable time after \overline{W} low	0	8	0	10	0	10	ns
tdis(OE)	Output disable time after \overline{OE} high	0	8	0	10	0	10	ns
ten(W)	Output enable time after \overline{W} high	0		0		0		ns
ten(OE)	Output enable time after \overline{OE} low	0		0		0		ns
tsu(A- \overline{WH})	Address to \overline{W} high	15		20		30		ns

(5) TIMING DIAGRAMS FOR WRITE CYCLE

Write cycle 1 (\overline{W} control mode)



Write cycle 2 ($\overline{S_1}$, S_2 control mode)



Note 5 When the falling edge of \overline{W} is simultaneous or prior to the falling edge of $\overline{S_1}$, S_2 , the output is maintained in the high impedance.

POWER DOWN CHARACTERISTICS ($T_a = 0 \sim 70^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
$V_{CC(PD)}$	Power down supply voltage		2			V
$V_I(\overline{S})$	Chip select input voltage	$V_I(\overline{S}) \geq V_{CC} - 0.2\text{V}$	$V_{CC} - 0.2$			V
$t_{su(PD)}$	Power down setup time	$V_I \geq V_{CC} - 0.2\text{V}$ or $0\text{V} \leq V_I \leq 0.2\text{V}$	0			ns
$t_{rec(PD)}$	Power down recovery time					ns
$I_{CC(PD)}$	Power down supply current	$V_{CC} = 3.0\text{V}$			50	μA
		$V_{CC} = 5.5\text{V}$			100	

Note 6. This is only M5M5279P, J-25L, -35L

TIMING WAVEFORM FOR POWER DOWN

